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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **Kunihiro KAKIHARA, et al.**

Serial No.: **Not Yet Assigned**  
(§371 of International Application PCT/JP05/08683)

Filed: **December 23, 2005**

For: **HEAT-TREATED RESIN MOLDINGS AND HEAT-TREATING APPARATUS FOR  
SAME**

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: December 23, 2005

Sir:

Prior to calculation of the filing fee and examination of this application, please amend the  
above-identified patent application as follows: